

ABSTRACT

DISPENSING SOLDER FOR MOUNTING SEMICONDUCTOR CHIPS

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A method for mounting a semiconductor chip onto a substrate comprises the steps of positioning a solder dispenser over the substrate and passing a length of solder wire through the solder dispenser to the substrate. The feeding of the wire to the substrate in a feeding direction is controlled with a wire feeder. The solder dispenser is moved relative to the substrate with a positioning device along at least one of two orthogonal axes that are substantially perpendicular to the feeding direction contemporaneously with feeding the solder wire to the surface of the substrate to dispense a line of molten solder onto the substrate. The semiconductor chip is then mounted onto the molten solder that has been dispensed onto the substrate.

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(FIG. 2)